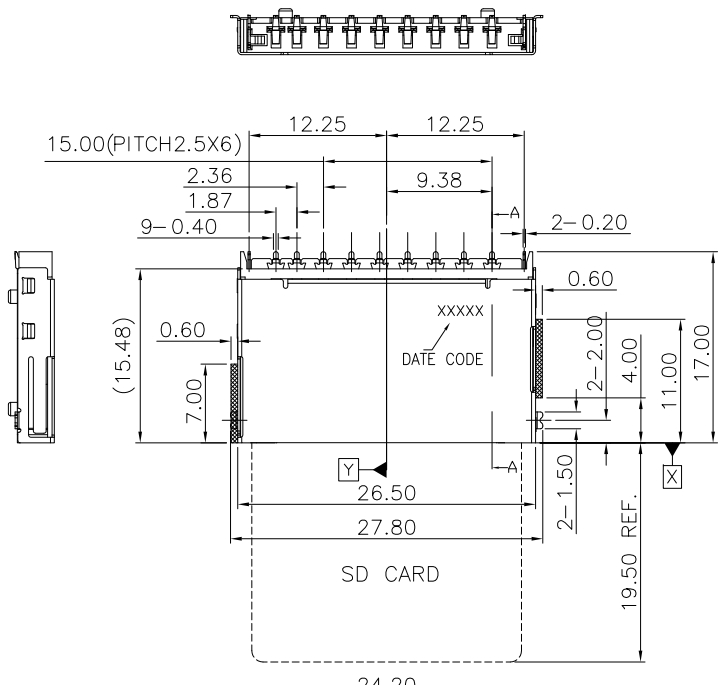
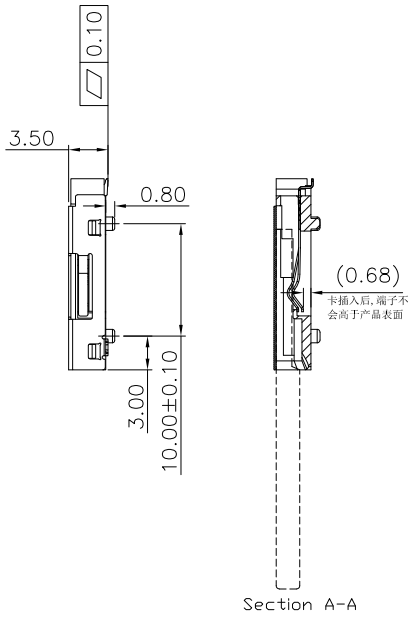
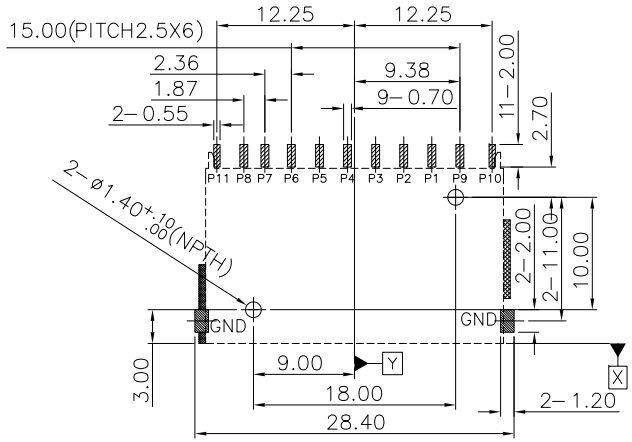
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2021/09/06	Hanson

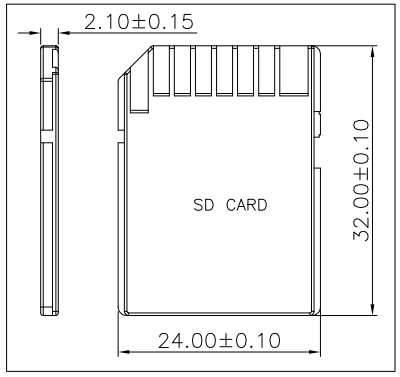






RECOMMENDED P.C.B LAYOUT
(General tolerance ±0.05)

- PAD AREA
- KEEP OUT AREA
- NO COPPER AREA (NO TRACE & VIA & GND)
- GND PATTERN ONLY



OPEN/CLOSE OF SD SWITCH:

- CD — GND: INSETION CARD:ON / NORMAL:OFF
- WP — GND: WRITE ENABLE:ON / WRITE PROTECTED:OFF / NORMAL:OFF

MATRIX PART NO:

MSD - 02 - 01 - 44 - HF

- Matrix SD
- 01: Push / 02: Non-Push
- Plating: 01:G/F / 30:30u"
- Series Number
- RS : ROHS / HF : Halogen Free

PIN NO.	NAME	DESCRIPTION
PIN1	CD/TAD3	CARD DETECT/DATA I/O
PIN2	CMD	COMMAND
PIN3	VSSI	GROUND
PIN4	VDD	POWER
PIN5	CLK	CLOCK
PIN6	VSS2	GROUND
PIN7	DAT0	DATA I/O
PIN8	DAT1	DATA I/O
PIN9	DAT2	DATA I/O
PIN10	CD	CARD DETECT
PIN11	WP	WRITE PROTECT

NOTES :

1. ELECTRICAL CHARACTERISTICS:
   CONTACT CURRENT RATING:0.5 A
   DIELECTRIC WITHSTANDING VOLTAGE: AC 500V r.m.s.
   INSULATION RESISTANCE:1000 MΩ Minimum.
   CONTACT RESISTANCE:100MΩ Maximum.
2. MATERIAL :
   INSULATOR : HIGH TEMPERATURE THERMOPLASTIC
   FLAMMABILITY RARING(LCP E130i) : UL94V-0 BLACK
   CONTACT : COPPER ALLOY(C5191-EH,T=0.15±0.03mm)
   COVER : STAINLESS(SUS301 3/4H,T=0.2±0.03mm)
3. Solder Tail Matte Tin(80u"Min)Plated Contact Area1u"Gold
4. When The Card Insertion,The Terminal Won't Touch The PCB Board
5. IR Reflow Temperature:260°,Immersing Time:5sec.
6. Durability Test Total:10000cycles.
7. Recommending A Metal More Than 0.15mm Thick. Please Confirm Solderability, IF Use A Metal Mask Less Than 0.15mm Thick.
8. This product is suitable for SD Card Association compliant cards.

Matrix Electronics Co.,Ltd

TOLERANCE: X: ±0.50, X.X ±0.38, X.XX ±0.25, X.XXX ±0.10, ANGLE: ±3°	DESIGN BY : Hanson Huang	DATE : 2021/09/06	PART NAME: SD NON PUSH	
UNIT: mm [inch]	CHECKED BY: Gorden Peng	DATE : 2021/09/06	PART NO.	MSD-02-01-44-HF
	APPROVED BY1: Richard Hsieh	DATE : 2021/09/06	MOLD NO.	NA
SCALE:1:1 SIZE:A4	APPROVED BY2: Richard Hsieh	DATE : 2021/09/06	DRAW NO.	
			SHEET NO.	1 OF 1